

CLMPTO
12/13/04
CM.

1. A method for forming a scribed groove at the surface portion of a wafer by using a cutting part having a cutting edge, the method comprising the step of moving the cutting part such that the cutting edge forms a path having the shape of an inverted trapezoid.
2. A method as defined by claim 1, the method further comprising the steps of:

 - (a) picking up the image of the cutting edge; and
 - (b) based on the picked-up image data, adjusting the angle of the cutting edge against the surface of the wafer.
3. A method as defined by claim 1, the method further comprising the steps of:

 - (a) measuring the thickness of the wafer; and
 - (b) in accordance with the measured thickness, adjusting the entry position of the cutting part into the wafer by combining the horizontal and vertical movements of the cutting part.

4. A method as defined by claim 2, the method further comprising the steps of:

- (a) measuring the thickness of the wafer; and
- (b) in accordance with the measured thickness, adjusting the entry position of the cutting part into the wafer by combining the horizontal and vertical movements of the cutting part.

CLAIMS 5-8. (CANCELLED)